X T Delta Printing System



First truly additive method for printing single micron functional structures











Benefits and advantages

- · Feature sizes down to submicron scale
- Wide range of material support
- Printing on heterogeneous materials and 3D topographies
- · Uniform & clean feature geometries: no overspray, high linewidth homogeneity
- Fast & easy exchange of cartridges & nozzles
- Only 0.1 ml of ink required to start printing
- Up to 100% ink utilization

Ultra-Precise Dispensing (UPD) technology

- Ultra-high-resolution printing on various substrates
- · High-viscosity materials along with small feature sizes
- High aspect ratios just after a single pass
- Wide range of printable materials: metallic nanoparticle inks and pastes, quantum dot inks, dielectrics, polymers, photoresists, organic, liquid metal alloys and more
- · Uninterrupted interconnections on highly complex topographies

Revolutionize your industry with the power of UPD



Semiconductors

- · High precision with submicron feature size
- A wide range of materials supported for varied semiconductor fabrication needs
- High aspect ratios, ideal for conductive power interconnections
- Quick process enhances efficiency and ensures uniform, reliable end products
- Printing on complex 3D surfaces More-than-Moore devices



- Biosensing pattern fabrication on flexible substrates, vital for wearable sensors
- Functionalized materials to prototype biosensors targeted at specific markers
- · Unparalleled precision for swift biosensor prototyping
- Ability to print structures through different types
 of microchannels



Printed Circuit Boards

- A wide variety of materials facilitating specific PCB structure creation and integration
- · High aspect ratio structures in a single pass
- Printing on complex 3D



Flexible Hybrid Electronics

- Superior precision for Flexible Hybrid Electronics manufacturing
- Reliable 3D chip interconnections directly on vertical slopes
- Conductive and non-conductive materials for complex circuit patterns and reliable interconnections
- High aspect ratios in a single pass
- Uniform, clean geometries promote FHE device performance and Radio Frequency (RF) capabilities



a-high resolution printing for OLED and

- Ultra-high resolution printing for OLED and microLED displays
- Precision ideal for interconnections, microcavity filling, and defect repair
- Dispensing of various display architecture elements, such as color conversion layers and interconnectors
- Single-step, high-precision additive process increases yield and reduces production time and costs

Unleash the power of cutting-edge technology!







Open defect repair



Microdots dispensing



Chip interconnection on flexible substrate



Filling the microwells and TSV



High-frequency structures

What sets technology apart and makes it the ideal choice for you?



Prof. Norbert Fruehauf, Director of IGM at University of Stuttgart

"The XTPL's ability to directly dispense (in a mask-less approach) electrically conductive structures in the minimum feature size range of 1.5 – 10 micrometers is unique. In my view the XTPL's ultra-precise dispensing technology offers truly unique properties, which are an excellent fit to the future needs in the field of printable high-resolution and foldable OLED displays."

Prof. Ravinder Dahiya, The Leader of the Bendable Electronics and Sustainable Technologies (BEST) Research Group at Northeastern University

*Our research revolves around the development of high-performance printed electronics and sensing systems on large area flexible substrates. We used these printed systems to develop flexible electronic skin (eSkin) and explore its application in healthcare, wearable systems and robotics. In our projects we also use micro/nanofabrication tools and align them with processing on flexible substrates. We decided to purchase the Delta Printing System for our labs, after performing initial tests with the team at XTPL over the last several months. This appears to be a great enabling tools and we are looking forward to including it in our daily research work."

DPS device details

Item	Value
Feature size range	ultra-high resolution from 0.5 μm to 1 μm
	high resolution from 1 μm to 10 μm
	medium resolution from 10 μm to 50 μm
Viscosity	from 10 to over 1 000 000 cP
Substrate alignment	3-point levelling table with rotation error correction
Printing area	200 mm x 200 mm
Maximum printing speed	10 mm/s
Process preview	Video feedback from 2 high-resolution and 1 top view cameras
XY motor movement accuracy / repeatability	2 μm / 0.5 μm
Z motor movement accuracy / repeatability (vertical adjustment)	0.5 μm / 0.5 μm
Printer cabinet dimensions (excluding peripherals and Printing Workstation)	1100 mm x 950 mm x 1925 mm

Contact our team

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For any product-related inquiries, contact our team members, who are readily available to provide you with professional and comprehensive assistance.

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